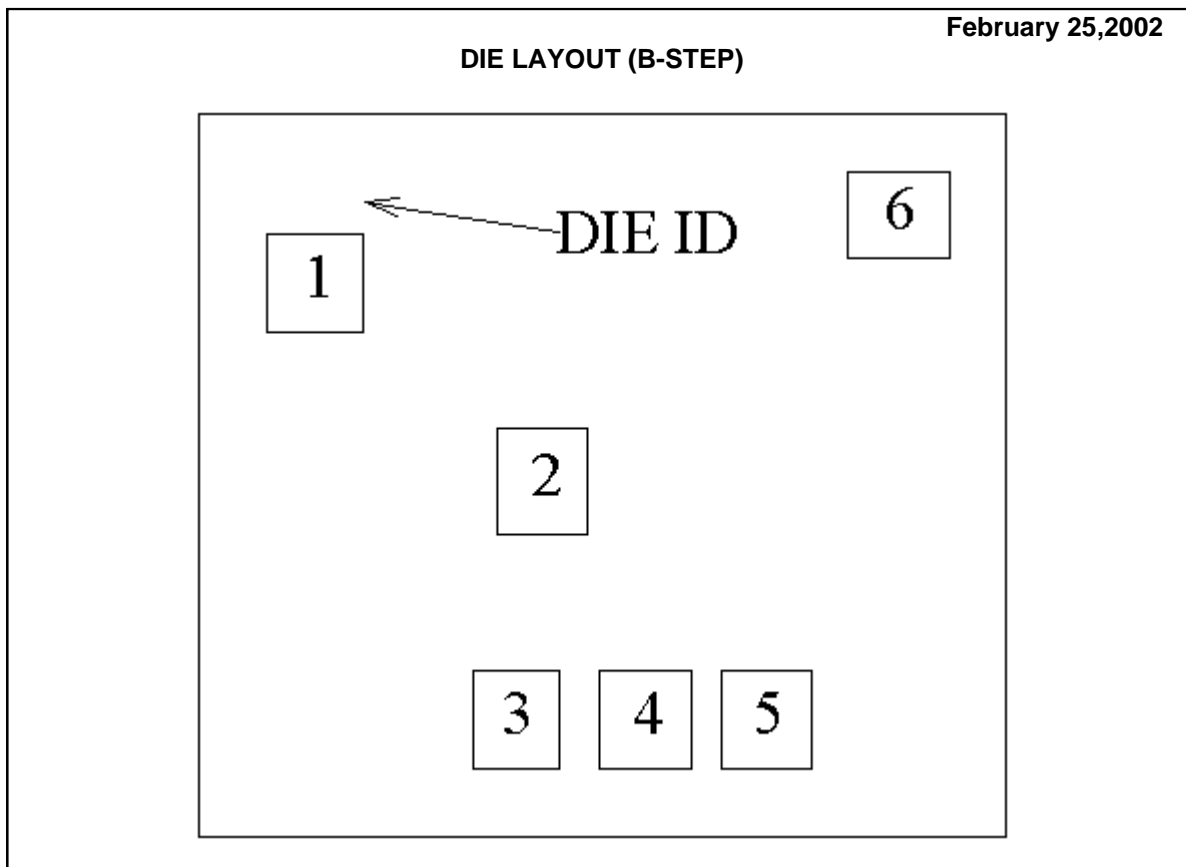


**LM334 MDC MWC**  
**3-TERMINAL ADJUSTABLE CURRENT SOURCE**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	134B	Bond Pad Opening Size (min)	104μm x 117μm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	864μm x 965μm 34mils x 38mils	Back Side Connection	V-
Thickness	330μm Nominal		
Min Pitch	143μm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
V+	1	-343	229	117	x	117
NC	2	-71	-8	107	x	127
V-	3	-103	-292	104	x	117
NC	4	52	-292	109	x	117
NC	5	196	-292	107	x	117
R	6	353	311	122	x	104

**LM334 MDC MWC**  
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